



IN THE U.S. PATENT AND TRADEMARK OFFICE

AF/2811

In re Application of: Yamaguchi, et al.

Serial No.: 10/087,556

Filed: 03/01/2002

For: Semiconductor Device and Bump Formation
Method

Docket No.: TI-31471

Examiner: Im, J.M.

Art Unit: 2811

Conf. No.: 2191

RECEIVED
SEP 26 2003
TECHNOLOGY CENTER 2800

APPEAL BRIEF TRANSMITTAL FORM

Commissioner for Patents

Alexandria, VA 22313-1450

Dear Sir:

<u>MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8 (A)</u>	
I hereby certify that on this day this correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
Elizabeth Austin	9/15/2003
Date	

Transmitted herewith in triplicate is an Appellant's Brief in the above-identified application.

Charge any additional fees, or credit overpayment to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Respectfully submitted,

Michael K. Skrehot
Attorney for Applicant
Registration No. 36,682

Texas Instruments Incorporated
P. O. Box 655474, M.S. 3999
Dallas, Texas 75265
(972) 917-5653